

ABSTRACT

The positive-type radiation-sensitive resin composition for producing a metal-plating formed material relating to the present invention comprises (A) a polymer containing a structural unit having an acid-dissociative functional group, which is dissociated in the presence of an acid to generate an acidic functional group, and a crosslinking structure; (B) a radiation-sensitive acid generator; and (C) an organic solvent.

The positive-type radiation-sensitive resin composition is excellent in sensitivity and resolution, exhibits excellent adhesion to a substrate, leaves no residue at an opening after development, and is capable of preventing occurrence of crack in the resin film after metal plating and push-in of plated metal into the resin film.